

AMENDMENT TO THE SPECIFICATION

Please replace the paragraph at page 11, lines 6-13 of the specification with the following new paragraph.

When the surface of the electrodes 52 in Fig. 6B is coated with a flux 54 ~~(not shown in the figure)~~, the solder balls 53 are adhesive bonded to the electrodes due to the adhesion thereof. When the surface of the electrodes 52 is not coated with a flux, semispherical bumps adhesive bonded to the respective electrodes 52 can be formed by, for example, reflowing the solder balls 53 in a reducing atmosphere, as referred to above.

AMENDMENT TO THE DRAWINGS

Please amend Fig. 6B of the drawings as shown in the attached sketch marked in red.